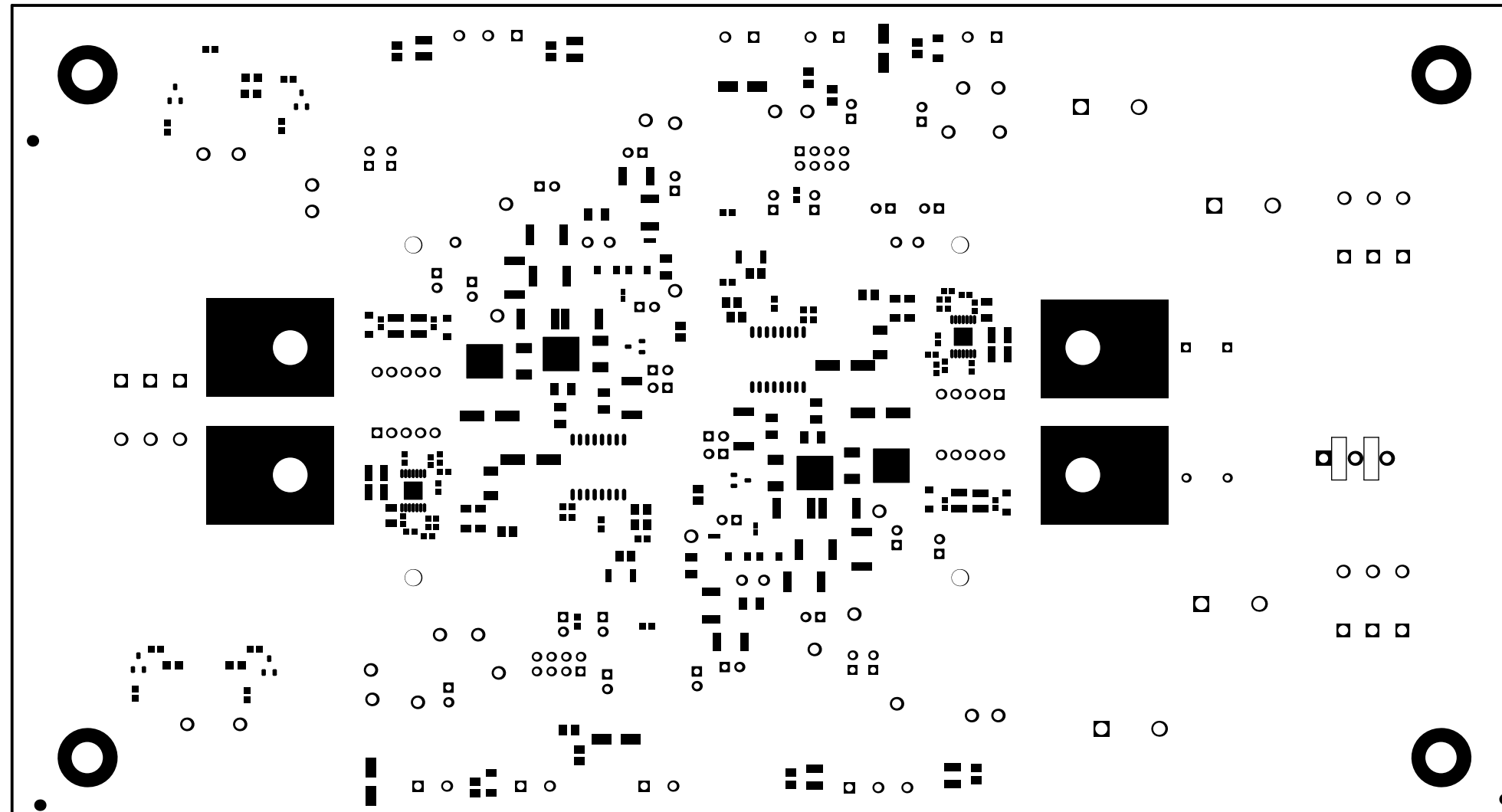
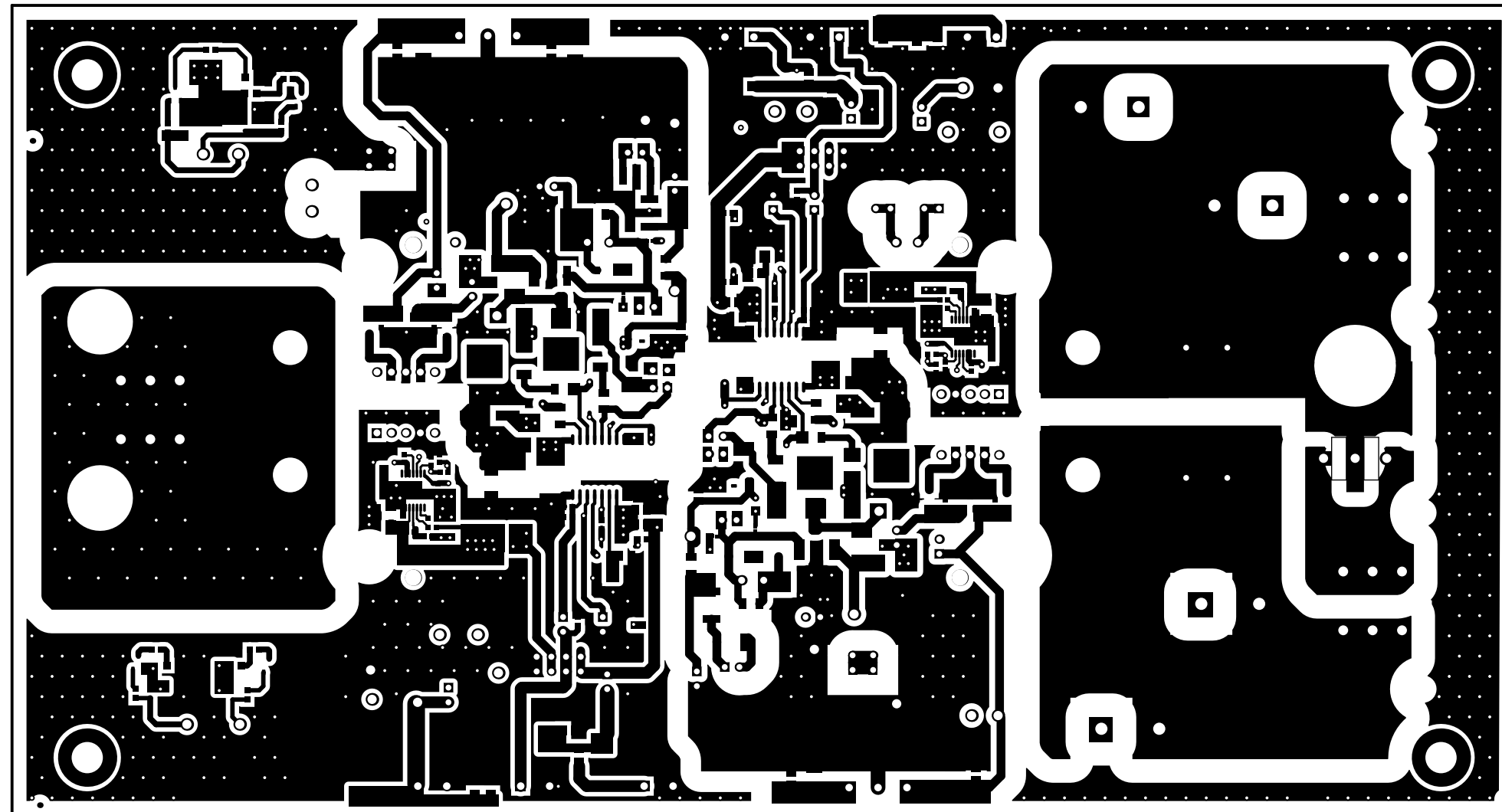


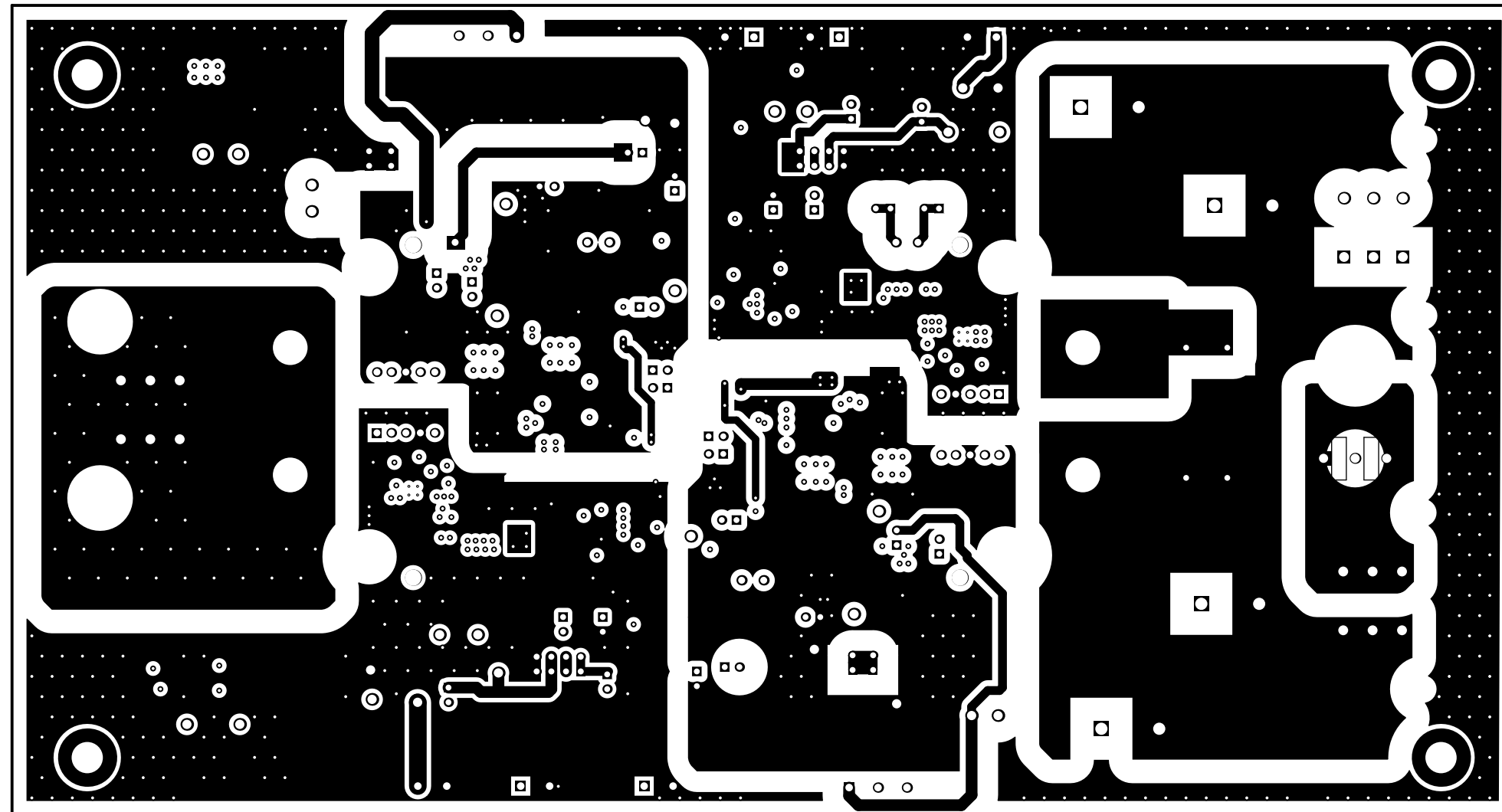
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00794	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00794		
PLOT NAME = Top Overlay	GENERATED : 3/23/2016 3:58:48 PM		TEXAS INSTRUMENTS



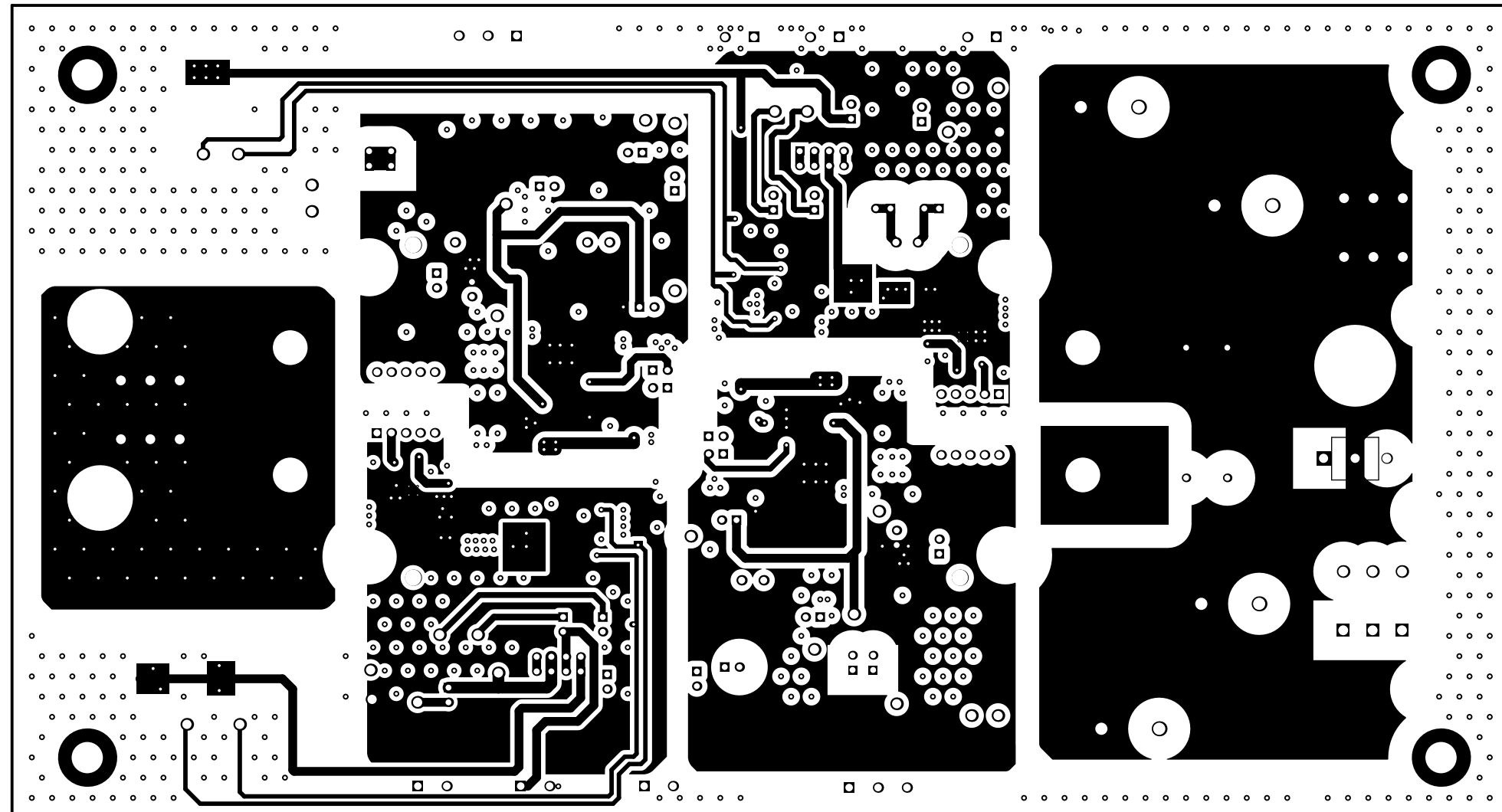
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00794	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00794		
PLOT NAME = Top Solder Mask	GENERATED : 3/23/2016 3:58:54 PM		TEXAS INSTRUMENTS



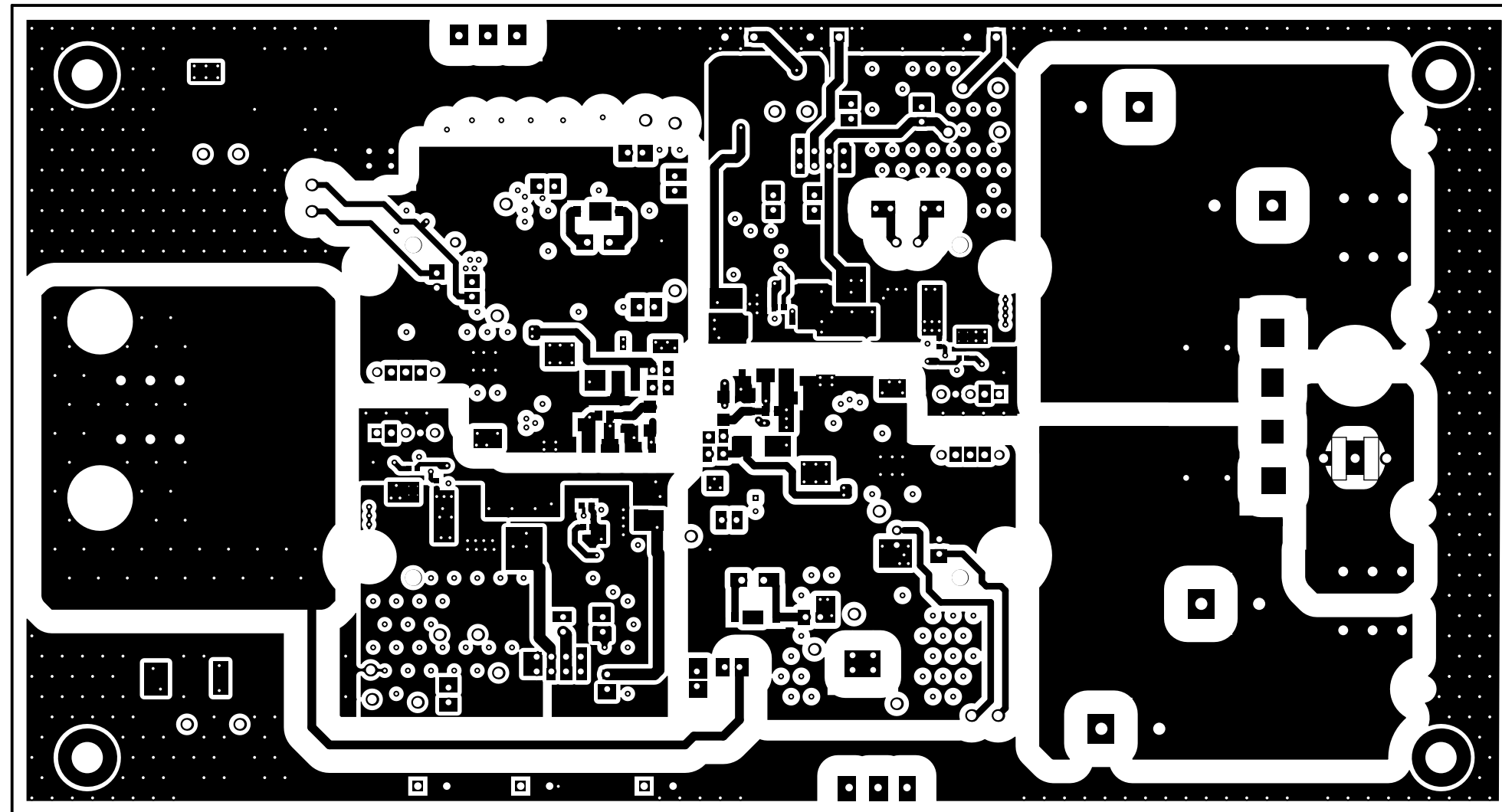
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00794	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00794		
PLOT NAME = Top Layer	GENERATED : 3/23/2016 3:58:59 PM		TEXAS INSTRUMENTS



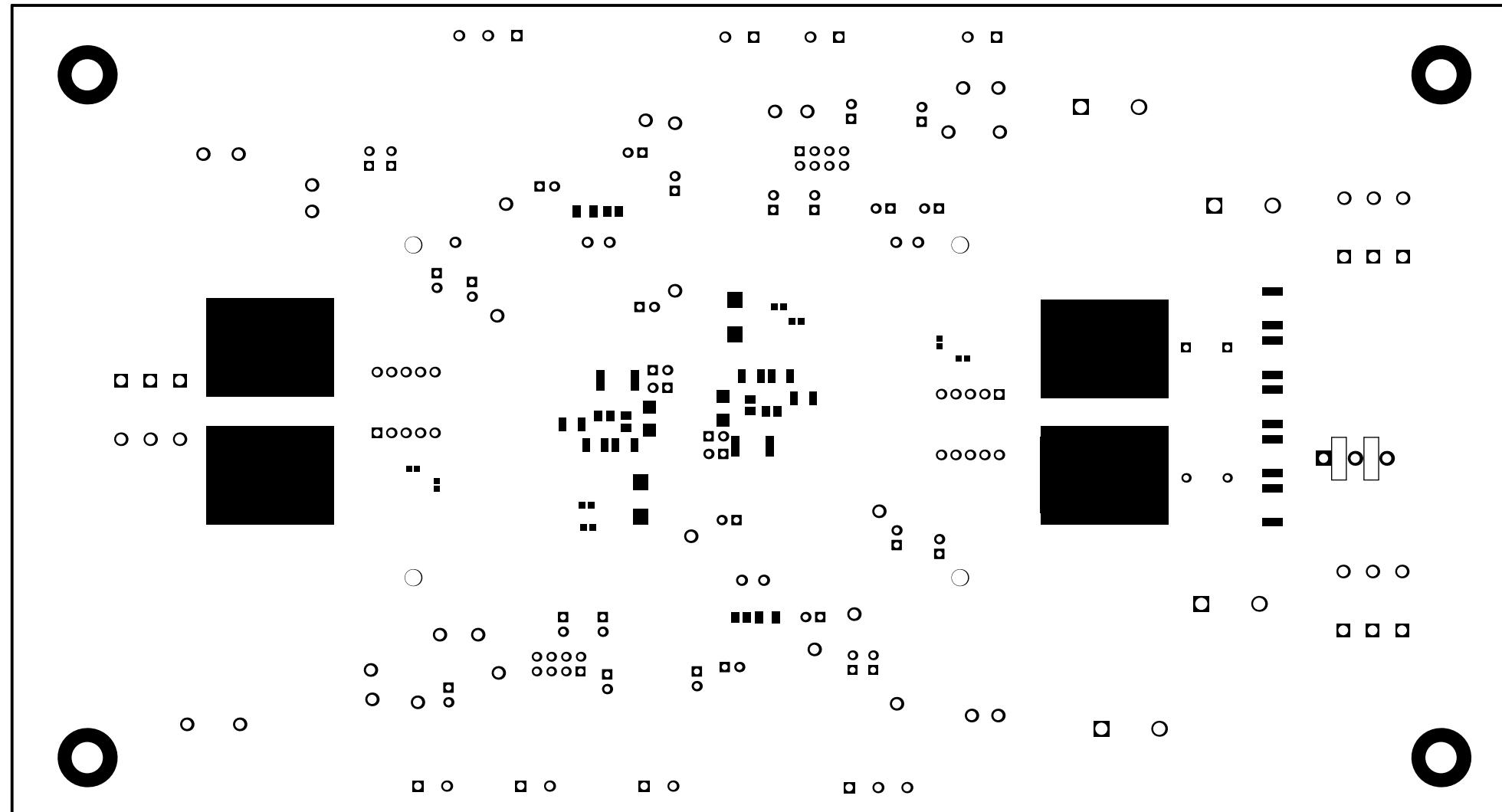
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00794	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00794		
PLOT NAME = Signal Layer 1	GENERATED : 3/23/2016 3:59:04 PM		TEXAS INSTRUMENTS



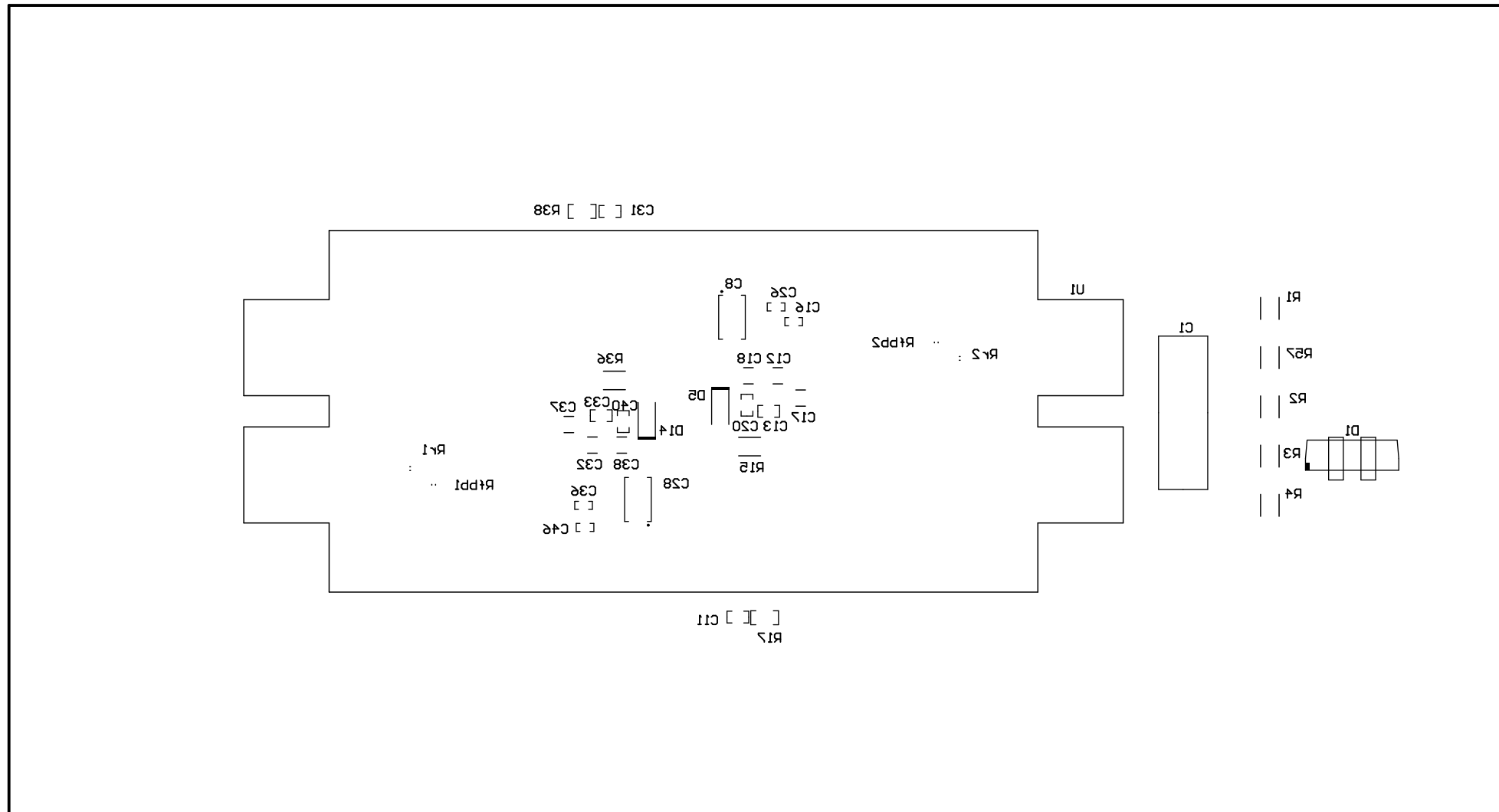
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00794	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-00794		
PLOT NAME = Signal Layer 2	GENERATED : 3/23/2016 3:59:09 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00794	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00794		
PLOT NAME = Bottom Layer	GENERATED : 3/23/2016 3:59:14 PM		TEXAS INSTRUMENTS



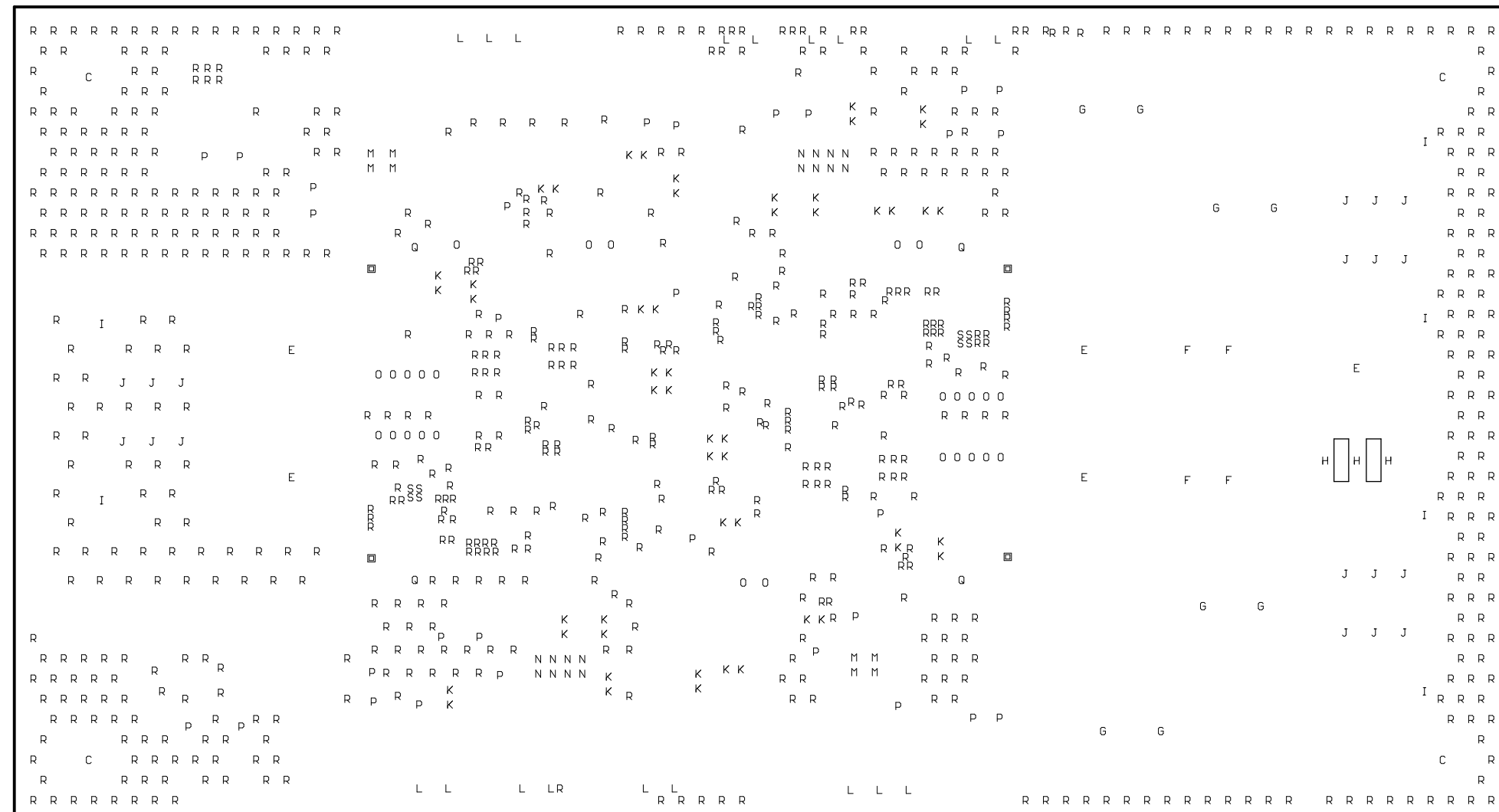
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00794	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00794		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/23/2016 3:59:20 PM		TEXAS INSTRUMENTS

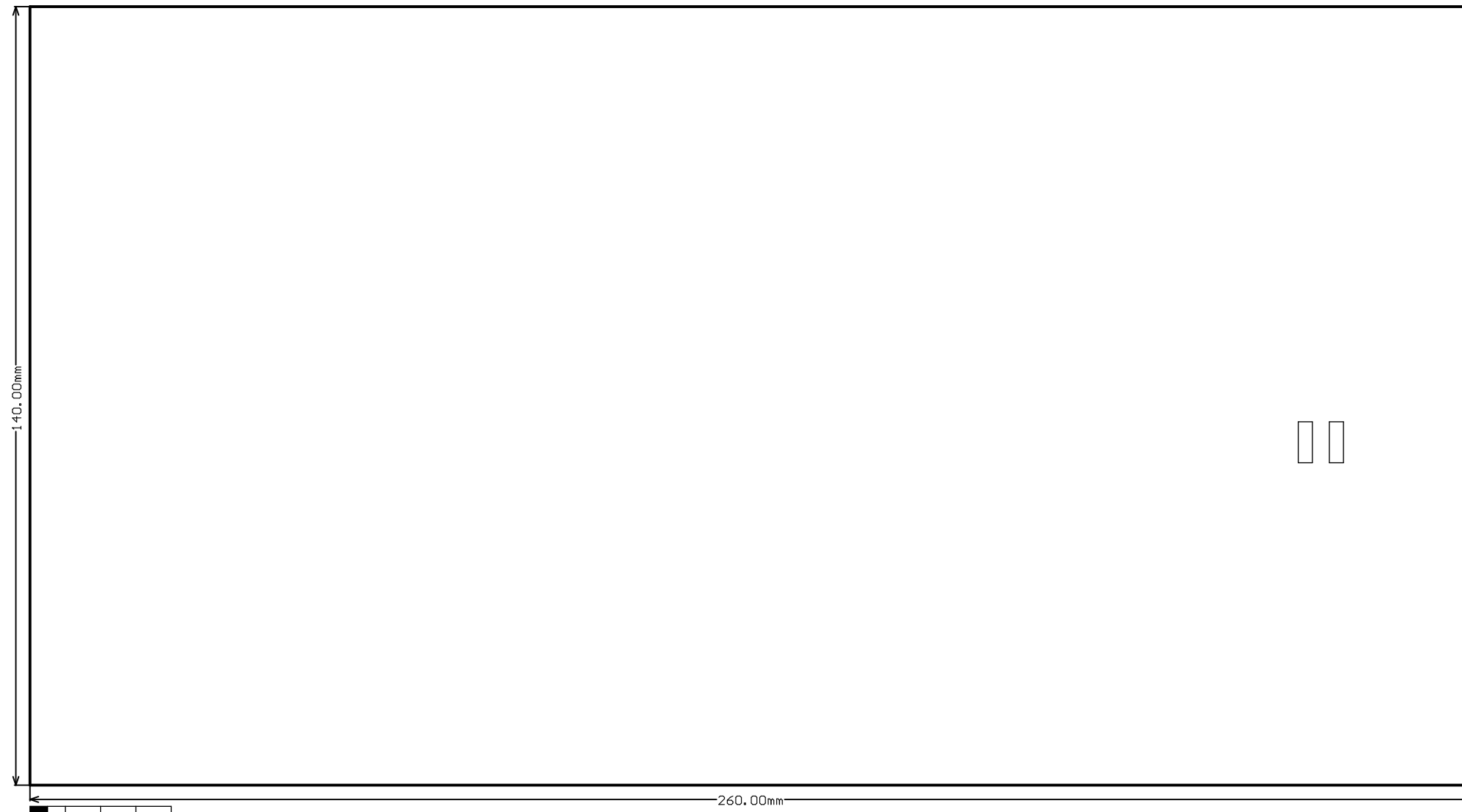


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00794	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00794		
PLOT NAME = Bottom Overlay	GENERATED : 3/23/2016 3:59:26 PM		TEXAS INSTRUMENTS



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
H	3	62.00mil (1.575mm)	PTH	Round
F	4	39.37mil (1.000mm)	PTH	Round
Q	4	110.24mil (2.800mm)	NPTH	Round
C	4	212.60mil (5.400mm)	PTH	Round
■	4	314.96mil (8.000mm)	PTH	Round
E	5	236.22mil (6.000mm)	PTH	Round
I	6	125.98mil (3.200mm)	NPTH	Round
S	8	7.87mil (0.200mm)	PTH	Round
M	8	40.16mil (1.020mm)	PTH	Round
G	8	82.68mil (2.100mm)	PTH	Round
N	16	40.94mil (1.040mm)	PTH	Round
L	18	51.18mil (1.300mm)	PTH	Round
J	18	66.93mil (1.700mm)	PTH	Round
O	27	47.24mil (1.200mm)	PTH	Round
P	30	63.00mil (1.600mm)	PTH	Round
K	52	40.00mil (1.016mm)	PTH	Round
R	717	20.00mil (0.508mm)	PTH	Round
	932 Total			





ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00794	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00794		
PLOT NAME = Board Dimensions	GENERATED : 3/23/2016 3:59:38 PM	TEXAS INSTRUMENTS	

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